



DS1489, DS1489A

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DS1489/DS1489A Quad Line Receiver

Check for Samples: DS1489, DS1489A

FEATURES

- Four Separate Receivers per Package
- **Programmable Threshold**
- **Built-in Input Threshold Hysteresis**
- "Fail Safe" Operating Mode: High Output for **Open Inputs**
- Inputs Withstand ±30V

DS1489: R_F = 10k DS1489A: R_F = 2k

SCHEMATIC AND CONNECTION DIAGRAMS

DESCRIPTION

The DS1489/DS1489A are guad line receivers designed to interface data terminal equipment with data communications equipment. They are constructed on a single monolithic silicon chip. These devices satisfy the specifications of EIA Standard RS-232D. The DS1489/DS1489A meet and exceed the specifications of MC1489/MC1489A and are pin-forpin replacements.



Dual-In-Line or Small-Out Line Package - Top View PDIP/SOIC

See Package Numbers NFF and D

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AC TEST CIRCUIT AND VOLTAGE WAVEFORMS



Figure 1.

ABSOLUTE MAXIMUM RATINGS (1)

If Military/Aerospace specified devices are required, contact the Texas Instruments Semiconductor Sales Office/ Distributors for availability and specifications.

| Power Supply Voltage | 10V |
|--|-----------------|
| Input Voltage Range | ±30V |
| Output Load Current | 20 mA |
| Power Dissipation ⁽²⁾ | 1W |
| Operating Temperature Range | 0°C to +75°C |
| Storage Temperature Range | −65°C to +150°C |
| Maximum Power Dissipation at 25°C ⁽³⁾ | • |
| Molded PDIP (NFF) Package | 1207 mW |
| SOIC (D) Package | 1042 mW |
| Lead Temperature (Soldering, 4 sec.) | 260°C |

(1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be ensured. Except for "Operating Temperature Range" they are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" provides conditions for actual device operation.

(2) Unless otherwise specified min/max limits apply across the 0°C to +75°C temperature range for the DS1489 and DS1489A.

(3) Derate molded PDIP package 9.7 mW/°C above 25°C; derate SOIC package 8.33 mW/°C above 25°C.



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ELECTRICAL CHARACTERISTICS (1) (2) (3)

DS1489/DS1489A: The following apply for $V_{CC} = 5.0V \pm 1\%$, 0°C $\leq T_A \leq +75$ °C unless otherwise specified.

| Symbol | Parameter | Conditions | | | Min | Тур | Max | Units |
|-----------------|------------------------------|---|-------------------------|-----------------------|-------|-------|------|-------|
| | Input High Threshold Voltage | V _{OUT} ≤ 0.45V, I _{OUT} = 10 mA | DS1489 | T _A = 25°C | 1.0 | 1.25 | 1.5 | V |
| V | | | | | 0.9 | | 1.6 | |
| ∨тн | | | DS1489A | T _A = 25°C | 1.75 | 2.00 | 2.25 | V |
| | | | | | 1.55 | | 2.40 | |
| V _{TL} | Input Low Threshold Voltage | V _{OUT} ≥ 2.5V, I _{OUT} = −0.5 mA | = -0.5 mA | | 0.75 | 1.00 | 1.25 | V |
| | | $I_{A} = 25^{\circ}C$ | | $I_{A} = 25^{\circ}C$ | 0.65 | | 1.35 | V |
| | | V _{IN} = +25V | | +3.6 | +5.6 | +8.3 | mA | |
| | Input Current | V _{IN} = -25V | | | -3.6 | -5.6 | -8.3 | mA |
| IIN | | V _{IN} = +3V | | | +0.43 | +0.53 | | mA |
| | | $V_{IN} = -3V$ | | | -0.43 | -0.53 | | mA |
| V | Output High Voltage | 0.5 m Å | V _{IN} = 0.75V | | 2.6 | 3.8 | 5.0 | V |
| VOH | | $I_{OUT} = -0.5 \text{ mA}$ Input = 0 | | า | 2.6 | 3.8 | 5.0 | V |
| V _{OL} | Output Low Voltage | V _{IN} = 3.0V, I _{OUT} = 10 mA | | | | 0.33 | 0.45 | V |
| I _{SC} | Output Short Circuit Current | V _{IN} = 0.75V | | | | -3.0 | | mA |
| I _{CC} | Supply Current | V _{IN} = 5.0V | | | | 14 | 26 | mA |
| Pd | Power Dissipation | V _{IN} = 5.0V | | | | 70 | 130 | mW |

 Unless otherwise specified min/max limits apply across the 0°C to +75°C temperature range for the DS1489 and DS1489A.
All currents into device pins shown as positive, out of device pins as negative, all voltages referenced to ground unless otherwise noted. All values shown as max or min on absolute value basis.

(3) These specifications apply for response control pin = open.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5V, T_A = 25^{\circ}C$

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|------------------|--|---|-----|-----|-----|-------|
| t _{pd1} | Input to Output "High" Propagation Delay | R _L = 3.9k, (Figure 1) (AC Test Circuit) | | 28 | 85 | ns |
| t _{pd0} | Input to Output "Low" Propagation Delay | $R_L = 390\Omega$, (Figure 1) (AC Test Circuit) | | 20 | 50 | ns |
| t _r | Output Rise Time | R _L = 3.9k, (Figure 1) (AC Test Circuit) | | 110 | 175 | ns |
| t _f | Output Fall Time | $R_L = 390\Omega$, (Figure 1) (AC Test Circuit) | | 9 | 20 | ns |

FEXAS NSTRUMENTS

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TYPICAL CHARACTERISTICS

 V_{CC} = 5.0V, T_A = +25°C unless otherwise noted









Figure 4.





V_I, INPUT VOLTAGE (Vdc) Figure 3.







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TYPICAL APPLICATION INFORMATION



*Optional for noise filtering.





Figure 9. Application of DS1488, DS1489A and UART

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REVISION HISTORY

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| Changed layout of National Data Sheet to TI format | ! | 5 |



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